



PK128 (v1.5) April 26, 2013

100% Material Declaration Data Sheet for VQG44 Package

Average Weight: 0.2677 g

| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|----------------|--------------------------------|---------------------------|-------------------------|----------------|--|----------------------------|
| Silicon Die | | | | | 0.003341 | 1.248 |
| | Silicon (Si) | 7440-21-3 | 100.00 | | 0.003341 | |
| Die Attach | | | | | 0.000921 | 0.344 |
| | Silver (Ag) | 7440-22-4 | 72.00 | | 0.000663 | |
| | Epoxy Resin | Trade Secret | 15.00 | | 0.000138 | |
| | Anhydride | Trade Secret | 10.00 | | 0.000092 | |
| | 1,4-Butanedioldiglycidyl ether | 2425-79-8 | 3.00 | | 0.000028 | |
| Mold Compound | | | | | 0.181160 | 67.681 |
| | Epoxy Resin | Trade secret | 7.00 | | 0.012681 | |
| | Phenol Resin | Trade secret | 5.00 | | 0.009058 | |
| | Carbon Black | 1333-86-4 | 0.30 | | 0.000543 | |
| | Fused Silica | 60676-86-0 | 87.70 | | 0.158877 | |
| Leadframe | | | | | 0.077366 | 28.904 |
| | Copper (Cu) | 7440-50-8 | 98.28 | | 0.076035 | |
| | Chromium (Cr) | 7440-47-3 | 0.25 | | 0.000193 | |
| | Tin (Sn) | 7440-31-5 | 0.25 | | 0.000193 | |
| | Zinc (Zn) | 7440-66-6 | 0.22 | | 0.000170 | |
| | Silver (Ag) | 7440-22-4 | 1.00 | | 0.000774 | |
| Solder Plating | | | | | 0.003502 | 1.308 |
| | Tin (Sn) | 7440-31-5 | 100.00 | | 0.003502 | |
| Gold Wire | | | | | 0.001376 | 0.514 |
| | Gold (Au) | 7440-57-5 | 99.00 | | 0.001362 | |
| | Palladium | 7440-05-3 | 1.00 | | 0.000014 | |

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Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|----------|---------|--|
| 03/16/06 | 1.0 | Initial Xilinx release. |
| 08/04/06 | 1.1 | 100% Material Declaration |
| 10/05/06 | 1.2 | Updated Component descriptions |
| 11/18/11 | 1.3 | Updated Component weights and descriptions |
| 08/24/12 | 1.4 | Updated CAS # in Die Attach |
| 04/26/13 | 1.5 | Updated CAS Description in Die Attach |

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